IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Ashjaee et al.

Serial No.: Not yet assigned

Filed: February 25: 2004

Group Art Unit: Not yet assigned

Examiner: Not yet assigned

Docket: NT-261C1-US

Title: Method Of Sealing Wafer Backside For

Full-Face Processing

INFORMATION DISCLOSURE STATEMENT

US PATENT DOCUMENTS

Examiner	Cite	Document Number	Publication Date	Name of Patentee or	
Initials,	No.			Applicant	
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Examiner	Cite	Document	Publication Date	Name of Patentee		Trans-		
Initials	No.	Number		or Applicant		lation		

OTHER DOCUMENTS

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Examiner Signature Date Considered 02/25/05.

Ser. No.: Not yet assigned